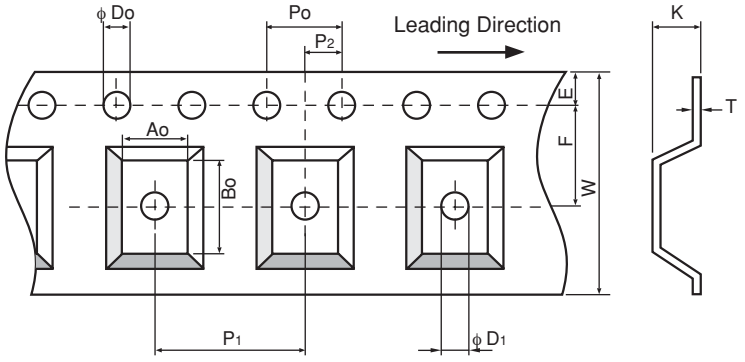
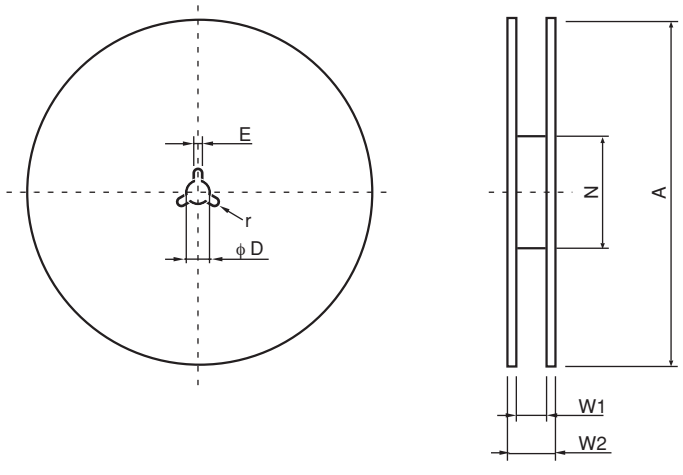
## ◆CARRIER TAPE DIMENSIONS




| Chip size | Taping code | Dimensions [mm] | | | | | | | | | | | |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| | | A0 ±0.1 | B0 ±0.1 | W ±0.3 | F ±0.05 | E ±0.1 | P1 ±0.1 | P2 ±0.04 | P0 ±0.1 | ϕ D0 ±0.1 | ϕ D1 +0.2/-0 | K ±0.1 | T ±0.05 |
| 3216 | A 1 | 2.00 | 3.60 | 8.0 | 3.5 | 1.75 | 4.0 | 2.0 | 4.0 | 1.5 | 1.0 | 1.4 | 0.20 |
| | A 2 | | | | | | | | | | | 1.8 | 0.25 |
| 3225 | B 1 | 2.90 | 3.60 | 8.0 | 3.5 | 1.75 | 4.0 | 2.0 | 4.0 | 1.5 | 1.0 | 1.8 | 0.25 |
| | B 2 | | | | | | | | | | | 2.2 | 0.25 |
| | B 3 | | | | | | | | | | | 2.4 | 0.25 |
| 4532 | C 1 | 3.60 | 4.90 | 12.0 | 5.5 | 1.75 | 8.0 | 2.0 | 4.0 | 1.5 | 1.5 | 1.8 | 0.25 |
| | C 2 | | | | | | | | | | | 2.2 | 0.25 |
| | C 3 | | | | | | | | | | | 2.4 | 0.25 |
| | C 4 | | | | | | | | | | | 3.0 | 0.25 |
| 5750 | D 1 | 5.40 | 6.10 | 12.0 | 5.5 | 1.75 | 8.0 | 2.0 | 4.0 | 1.5 | 1.5 | 2.2 | 0.25 |
| | D 2 | | | | | | | | | | | 2.6 | 0.25 |
| | D 3 | | | | | | | | | | | 3.0 | 0.25 |

## ◆REEL DIMENSIONS




| Chip size | Reel size | Quantity |
|---|---|---|
| 3216 | ϕ 180mm | 2000pcs/reel |
| 3225 | ϕ 180mm | 2000pcs/reel |
| 4532 | ϕ 254mm | 1500pcs/reel |
| 5750 | ϕ 254mm | 1500pcs/reel |

(mm)

| Taping code | A | N | W 1 | W2 | D | E | r |
|---|---|---|---|---|---|---|---|
| A, B | ϕ 180 ± 1.0 | ϕ 60 ±1.0 | 9.5 ± 1.0 | 13.1 ± 1.0 | ϕ 13.0 ± 0.2 | 2.0 ± 0.5 | 1.0 ± 0.2 |
| C, D | ϕ 254 ± 1.0 | ϕ 100 ± 1.0 | 13.5 ± 1.0 | 18.5 ± 1.0 | ϕ 13.0 ± 0.2 | 2.0 ± 0.5 | 1.0 ± 0.2 |

# ● SOLDERING CONDITIONS

## ◆REFLOW SOLDERING CONDITIONS

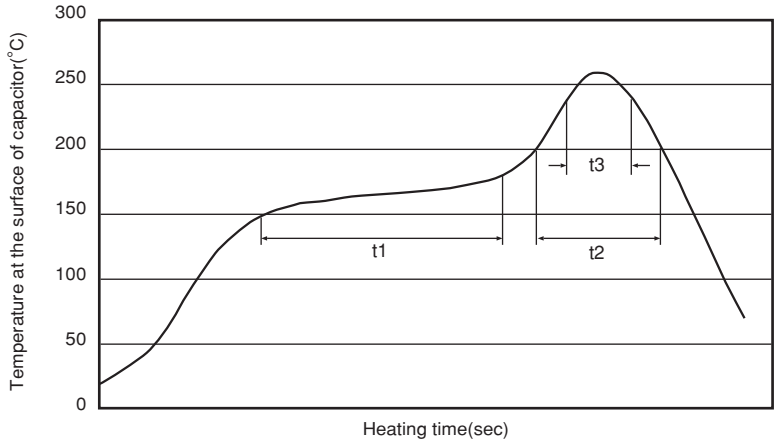
1)Surface temperature of capacitor shall not exceed the value shown in the following table.

2)Period that temperature at surface of capacitor becomes more than 200°C and 240°C temperature shall not exceed t2 and t3 seconds shown in the following table, respectively.

3)Holding time at the peak temperature shall be as short as possible.

4)Preheat temperature shall be made between 150 to 180°C and made maximum t1 seconds shown in the following table.

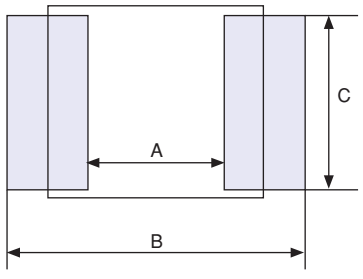
5)Soldering frequency shall be less than 2 times. The second soldering should be carried after the surface tenperature of capaitor has returned to normal temperature.




| | (T) | (t1) | (t2) | (t3) |
|---|---|---|---|---|
| 150～180°C | 260°C | 180sec | 90sec | 40sec |

## ◆RECOMMENDED LAND SIZE

For designing land size, refer to the following recommended land size.




| Chip size | Dimensions(mm) | | |
|---|---|---|---|
| | A | B | C |
| 3216 | 1.8 | 3.6 | 1.4 |
| 3225 | 1.8 | 3.6 | 2.3 |
| 4532 | 2.7 | 5.7 | 3.0 |
| 5750 | 3.5 | 7.8 | 4.5 |